SLIDE.

TECHNICAL DATA SHEET





Faster, more efficient for high-temp resins





Hi-Temp Purge Compound 478-45, 478-1000

Product Description

Hi-Temp Purge Compound is Slide's answer to those jobs where presses are run at temperatures between 485° and 750°F. This formulation aids with the purging of engineering-grade resins, and safely cleans screws and barrels with virtually no odor or smoke. It can remove burned material, color hang-ups, resin deposits, black specks and also soften and remove rust. Hi-Temp is a chemically reactive, non-abrasive purge utilizing a PET carrier resin. While it is not recommended for cleaning hot runners, it is effective for use with injection molding and is ideal for resins such as PPS, PEEK, PET, LCP and PEI (Ultem[™]). All ingredients are GRAS rated so it is safe to use for food packaging applications.

Applications	Purging Compound
Unit Package Description	49 and 1100 pound boxes
Generic Description	Purging Compound
Net Weight Fill	45 & 1,000 pounds
UPC Code	858799000783
Appearance	Resin Pellet
Odor	None
Flash Point F	N/A
Flash Point C	N/A
Base Type	Resin
Evaporation Rate	N/A
HMIS Rating	0, 0, 0, None
DOT Proper Shipping Name	Not regulated, Granules, NOI
Removal	N/A
Units Per Case	45 & 1,000 pounds
Case Weight (Ibs)	45 / 1,000
Working Temperature F	485 to 750 degrees
Working Temperature C	250 to 395 degrees
Propellant	N/A
NFPA Aerosol Flammability Level	N/A